Product Change Notification: DSNO-23ZLEM284

Date:

29-Jul-2025

Product Category:

Photoelectric/Ionization Smoke Detector

Notification Subject:

CCB 7734 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as new bond wire material for RE370V28, RE370V28T, RE46C400V28, RE46C400V28T, RE46C401V28, RE46C401V28T, RE46C420V28T, RE46C421V28T, RE46C422V32, RE46C422V32T, RE46C700IV28, RE46C700IV28T, RE46C701IV28, RE46C701IV28T, RE46C705IV32, RE46C705IV32T, RE46C730IV28 and RE46C730IV28T catalog part numbers (CPN) available in 28L VQFN (4x4x1.0mm) and 32L VQFN (5x5x1mm) packages at MTAI assembly site.

Affected CPNs:

DSNO-23ZLEM284_Affected_CPN_07292025.pdf
DSNO-23ZLEM284_Affected_CPN_07292025.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as new bond wire material for RE370V28, RE370V28T, RE46C400V28, RE46C400V28T, RE46C401V28, RE46C401V28T, RE46C420V28T, RE46C421V28T, RE46C422V32, RE46C422V32T, RE46C700IV28, RE46C700IV28T, RE46C701IV28, RE46C701IV28T, RE46C705IV32, RE46C705IV32T, RE46C730IV28 and RE46C730IV28T catalog part numbers (CPN) available in 28L VQFN (4x4x1.0mm) and 32L VQFN (5x5x1mm) packages at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change

Assembly Site	Microchip Technology Thailand (HQ) (MTAI)		Microchip Technology Thailand (HQ) (MTAI)	
Wire Material	Au		CuPdAu	
Die Attach Material	3280		*QMI519	
Molding Compound Material	G700LTD		G700LTD	
Lead-Frame Material	C194		C194	
DAP Surface Prep	Ag	Bare Cu	Ag	Bare Cu

Note 1: *PFAS-free material.

Note 2: *The qualification of the new PFAS-free die attach material, QMI519, was officially released via PCN #CENO-16EGCZ399.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire as a new wire material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: September 2025

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	July 2025					>	**September 2025**				
Work Week	27	28	29	30	31		36	37	38	39	40
Initial PCN Issue Date					X						

Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: July 29, 2025: Issued initial notification. The new die attach material was qualified via PCN #**CENO-16EGCZ399** on July 22, 2025.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-23ZLEM284_Qualification_Plan.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

RE370V28

RE370V28T

RE46C400V28

RE46C400V28T

RE46C401V28

RE46C401V28T

RE46C420V28T

RE46C421V28T

RE46C422V32

RE46C422V32T

RE46C700IV28

RE46C700IV28T

RE46C701IV28

RE46C701IV28T

RE46C705IV32

RE46C705IV32T

RE46C730IV28

RE46C730IV28T